MSKSEMI 美森科













ESD

'S

SS

MOV

GDT

PLED

RB521S30T1G(MS)

Product specification





Features

- UltraSmallmoldtype.(SOD-523)
- LowIR
- Highreliability.

Applications

Lowcurrentrectification

Construction

Siliconepitaxialplanar

MechanicalCharacteristics

- Leadfinish:100%matteSn(Tin)
- Mountingposition:Any
- Qualifiedmaxreflowtemperature:260 °C
- DevicemeetsMSL1requirements
- Puretinplating:7~17um
- Pinflatness:≤3mil

Reference News

Outline	Pin Configuration	Marking	
		5M *	
SOD-523			

Electricalcharacteristicsperline@25℃

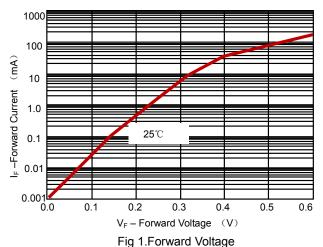
Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward voltage	VF	-	-	0.5	V	l⊧=200mA
Reverse current	I R	-	-	30	μΑ	V _R =10V

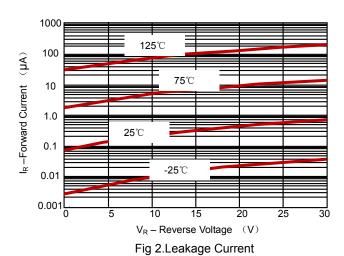
Absolute maximum rating@25℃

Parameter	Symbol	limits	Unit
Reverse voltage (DC)	V _{RM}	30	V
Average rectified forward current	Ь	200	mA
Forward current surge peak (60Hz 1cyc)	İfsm	1	А
Operating Junction temperature Range	Tj	-55 to 125	°C
Storage temperature	Tstg	-40 to +125	°C



Typical Characteristics





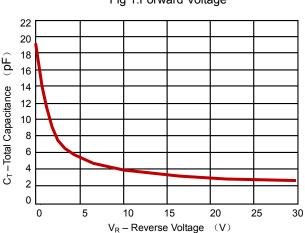
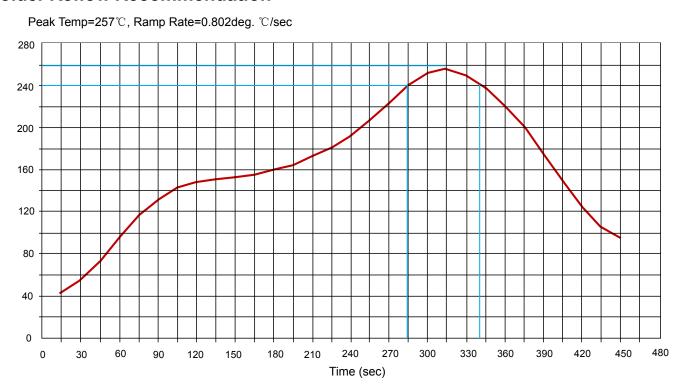


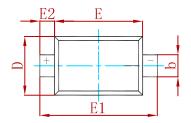
Fig 3.Total Capacitance

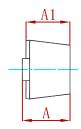
Solder Reflow Recommendation

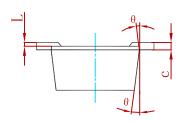




PACKAGE MECHANICAL DATA

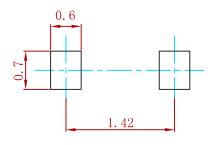






Symbol	Dimensions In Millimeters		Dimensions In Inches		
Syllibol	Min	Max	Min	Max	
Α	0.510	0.770	0.020	0.031	
A1	0.500	0.700	0.020	0.028	
b	0.250	0.350	0.010	0.014	
С	0.080	0.150	0.003	0.006	
D	0.750	0.850	0.030	0.033	
E	1.100	1.300	0.043	0.051	
E1	1.500	1.700	0.059	0.067	
E2	0.200 REF		300.0	REF	
L	0.010	0.070	0.001	0.003	
θ	7° F	REF	7° F	REF	

Suggested Pad Layout



Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

REELSPECIFICATION

P/N	PKG	QTY
RB521S30T1G(MS)	SOD-523	3000



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